

ABSTRACT OF THE DISCLOSURE

A semiconductor package includes: a first package substrate; a first semiconductor device mounted on the first package substrate; a second package substrate arranged on an upper part of the first semiconductor device; and a heat-dissipating material layer arranged between the first semiconductor device and the second package substrate and having a thermal conductivity of approximately $0.5 \text{ W/m}\cdot\text{K}$ to approximately $20 \text{ W/m}\cdot\text{K}$, wherein the heat-dissipating material layer is in direct contact with an upper surface of the first semiconductor device and a conductor of the second package substrate.

FIG. 1